

1. (Amended) A method for making a multisheet sandwich panel having a superplastically formed core of metal sheets, adhesively bonded with a polymer film to outer face sheets, being formable superplastically in a superplastic forming temperature range, comprising the steps of:

(a) assembling a pack of a plurality of sheets of sheet metal having a high temperature polymer film adhesive affixed to at least one ~~or more~~ sheet at selected locations corresponding to the location of adhesive bonds in the finished part;

(b) loading the pack to a press;

(c) heating the pack to the superplastic forming range without destroying the polymer film adhesive;

(d) superplastically forming the pack to define a selected core geometry for the finished part and to define ~~the~~ polymer film adhesive bonds;

(e) flowing the polymer film adhesive concurrently with forming the pack to produce polymer film adhesive bonds in desired locations;

(f) cooling the formed pack below the superplastic range to a temperature where the polymer film adhesive sets to complete the finished part; and

(g) removing the cooled, finished part from the press.

2. (Original) The product obtained by the SPF/AB method of claim 1.

3. (Original) The product of claim 2 wherein the sheets are aluminum alloy and the adhesive is a polyimide.

4. (Amended) A combined cycle method for superplastically forming and adhesively bonding a multisheet part, especially one having aluminum face sheets and core sheets, with a polymer film adhesive comprising the step of:

adhesively bonding using a polymer film adhesive between a core pack with outer face sheets in the part ~~with~~ while superplastically forming the core pack.

5. (Original) An SPF/AB part made by the method of claim 4.

6. (Original) The process of claim 1 wherein the metal sheets are A1 2004, A1 8090, or A1 1570 and the adhesive is a polyimide.

7. (New) The method of claim 4 wherein the adhesive is a polyimide.

8. (New) The method of claim 1 wherein forming occurs below 425°C.

9. (New) The method of claim 4 wherein forming occurs below 425°C.

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